

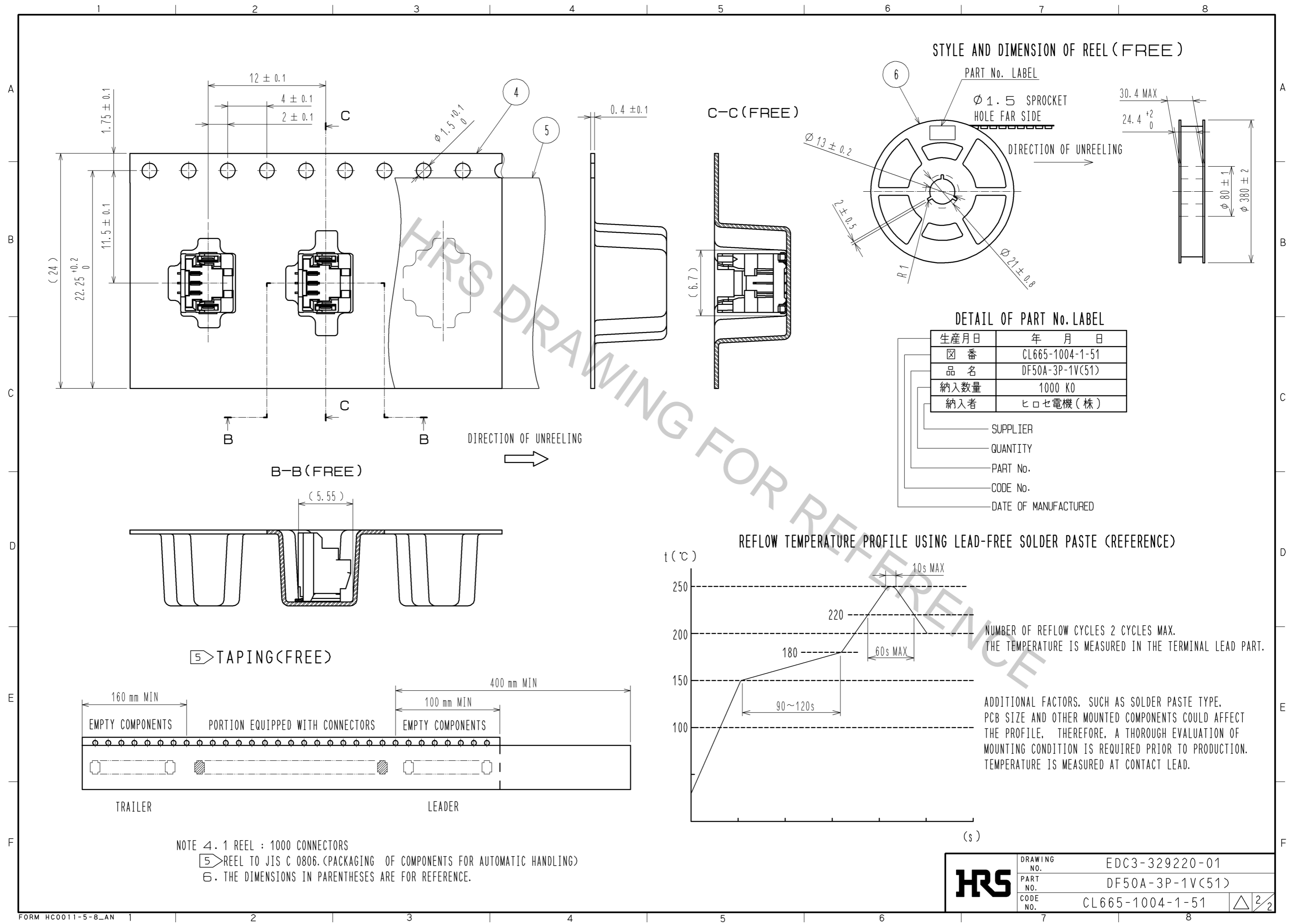
RECOMMENDED PCB LAYOUT  
(MOUNTING SURFACE SIDE) (FREE)

RECOMMENDED METAL MASK (FREE)  
THICKNESS : 0.1mm  
OPEN AREA RATIO:100%

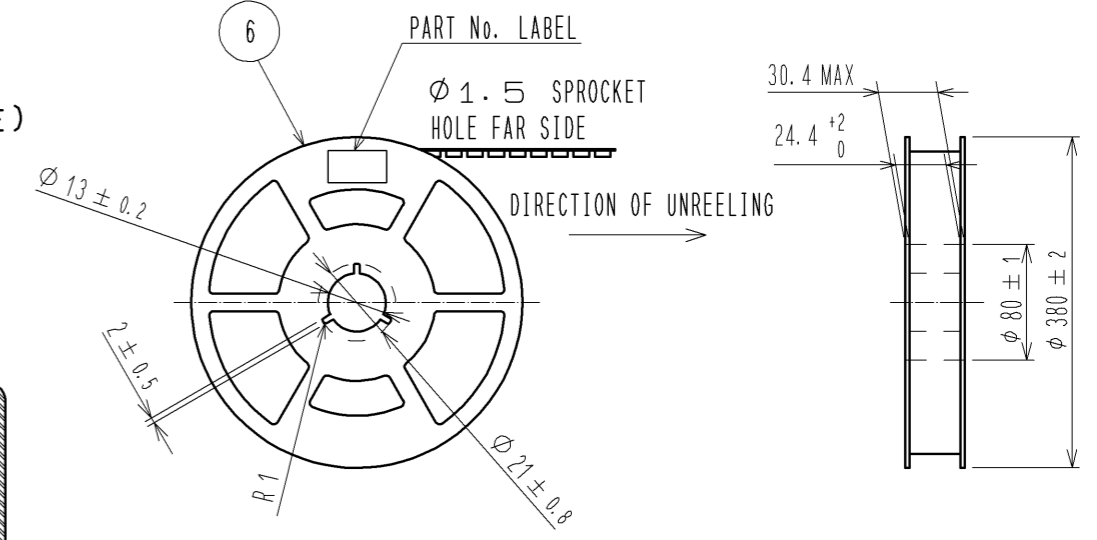
MATING FIGURE(5:1)

- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX  
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.  
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	PHOSPHOR BRONZE	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Cu PLATING 0.3μm MIN			
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	6	PS	REEL . BLACK
1	LCP	BLACK . UL94V-0	5	POLYESTER	CLEAR
			4	PS	CLEAR
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 5 : 1	COUNT		DESCRIPTION OF REVISIONS
DESIGNED		CHECKED		DATE	
APPROVED : KI. AKIYAMA		12.06.19		DRAWING NO. EDC3-329220-01	
CHECED : HK. UMEHARA		12.06.19		PART NO. DF50A-3P-1V(51)	
DESIGNED : ST. SATO		12.06.19		CODE NO. CL665-1004-1-51	
DRAWN : ST. SATO		12.06.19		1/2	



STYLE AND DIMENSION OF REEL (FREE)

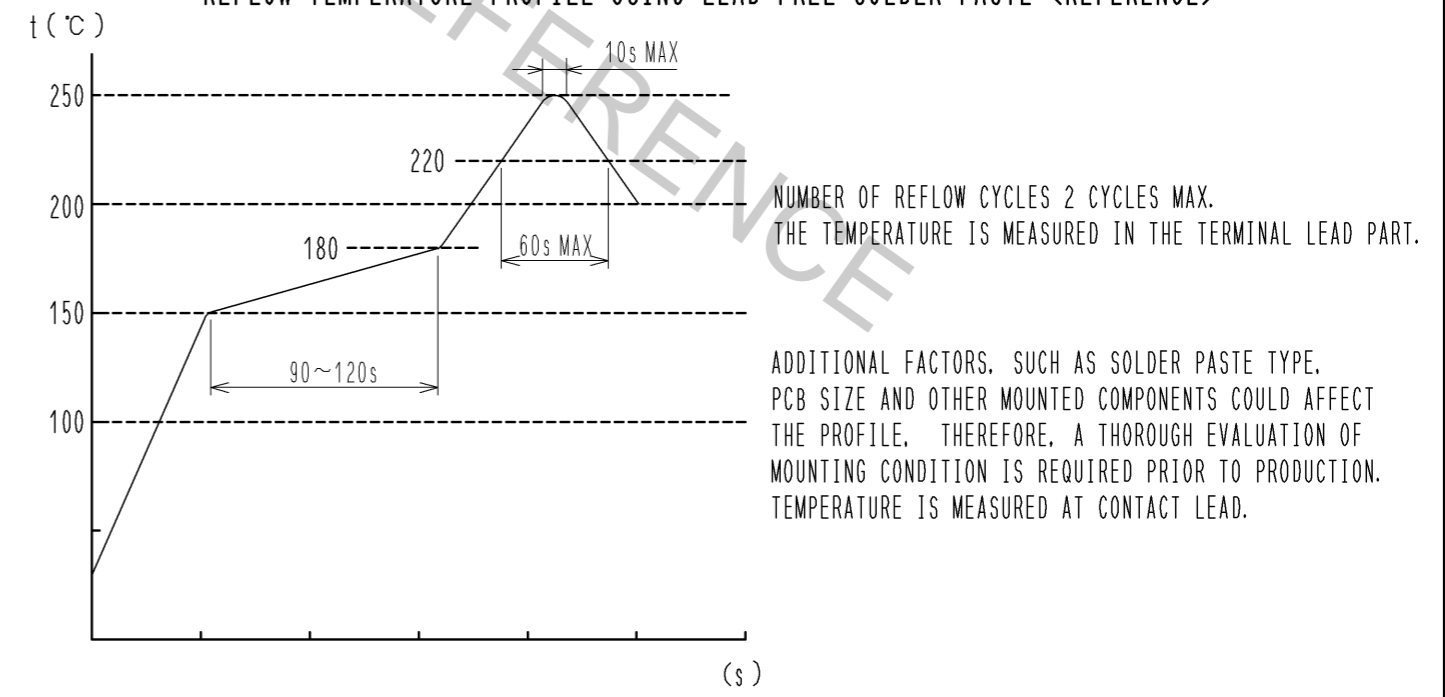


DETAIL OF PART No. LABEL

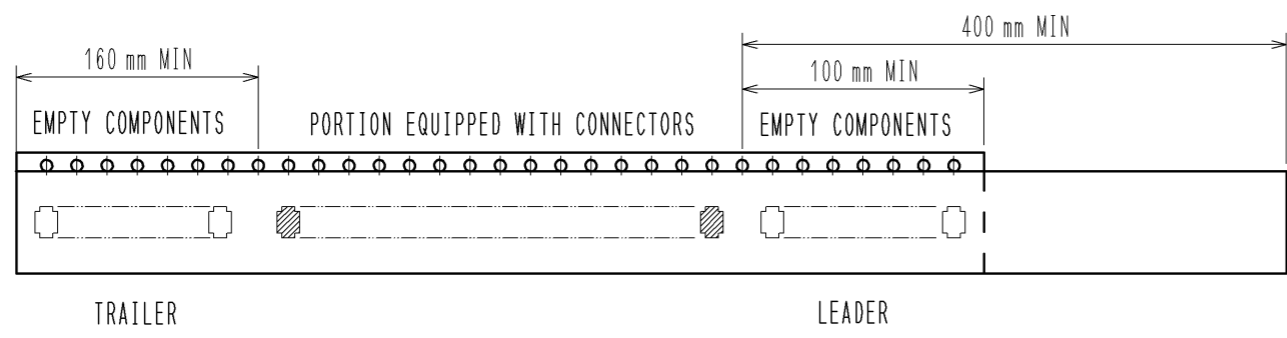
生産月日	年 月 日
箱 番	CL665-1004-1-51
品 名	DF50A-3P-1V(51)
納入数量	1000 K0
納入者	ヒロセ電機(株)

- SUPPLIER
- QUANTITY
- PART No.
- CODE No.
- DATE OF MANUFACTURED

REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



5 TAPING(FREE)



NOTE 4. 1 REEL : 1000 CONNECTORS  
 5 REEL TO JIS C 0806. (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)  
 6. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

<b>HRS</b>	DRAWING NO.	EDC3-329220-01
	PART NO.	DF50A-3P-1V(51)
	CODE NO.	CL665-1004-1-51
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